



3DS-IC TC Taiwan Chapter Staff Report

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SEMI Global 2016 Calendar of Events

	Event Name	Event Details
	SEMICON Korea	January 27-29, 2016 Seoul, Korea
	SEMICON China	March 15-17, 2016 Shanghai, China
	SEMICON Southeast Asia	26 - 28 Apr, 2016 Penang, Malaysia
	Advanced Semiconductor Conference	May 16-19, 2016 Saratoga Spring, NY
	SEMICON Russia	8-9 June, 2016 Moscow, Russia
	SEMICON West	July 12-14, 2016 San Francisco, California
	SEMICON Taiwan	September 7-9, 2016 Taipei, Taiwan
	SEMICON Europa	October 25-27, 2016 Grenoble, France
	SEMICON Japan	December 14-16, Tokyo, Japan

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2016 Critical Dates for SEMI Standards Ballots

Cycle	Ballot Submission Date	Voting Period Starts	Voting Period Ends
1	January 4	January 12	February 12
2	February 2	February 16	March 17
3	March 1	March 14	April 13
4	April 15	April 26	May 26
5	May 10	May 24	June 23
6	July 22	August 1	September 1
7	August 17	August 31	September
8	October 17	October 24	November
9	November 16	November 30	December



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2016 SEMI Training course topics:

- 3/21 : EHS and Sustainable Manufacturing Seminar (completed)
- 3/30 : Learn the Importance of Disaster Recovery from Ten-Billion Loss. (completed)
- 5/4 : Introduction of Water footprint (completed)
- • 6/15 : Semiconductor Tool and Parts Decontamination - Decommission (Basic)
- 9/23 : Semiconductor Tool and Parts Decontamination – Team-based and Practice-based Learning (Advanced)

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From: SEMI NA staff

Discuss #5174 to establish the global TF team ?

- Doc. 5174: New Standard: Specification for Identification and Marking for Bonded Wafer Stacks
- Rationale:

Current wafer identification standards and wafer marking standards do not adequately address the needs of bonded wafer stacks. Location (e.g. backside near notch for SEMI T7) will be removed during backside thinning operations or edge-trim operations, or buried under an opaque layer of silicon and rendered unreadable by optical readers when bonded. Multiple wafer stacks will combine wafers with multiple process history, including tracking of temporary carrier wafers, and a standard needs to be developed to combine and track bonded wafer stacks with multiple wafer histories.

- Scope:

Develop an identification standard that will meet the needs of bonded wafer stacks. The initial focus will be temporary bonding and permanent bonding as driven by contributions.

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- Japan TC Chapter of Global Automated Test Equipment Technical Committee was disbanded at the JRSC Meeting during SEMICON Japan 2015.